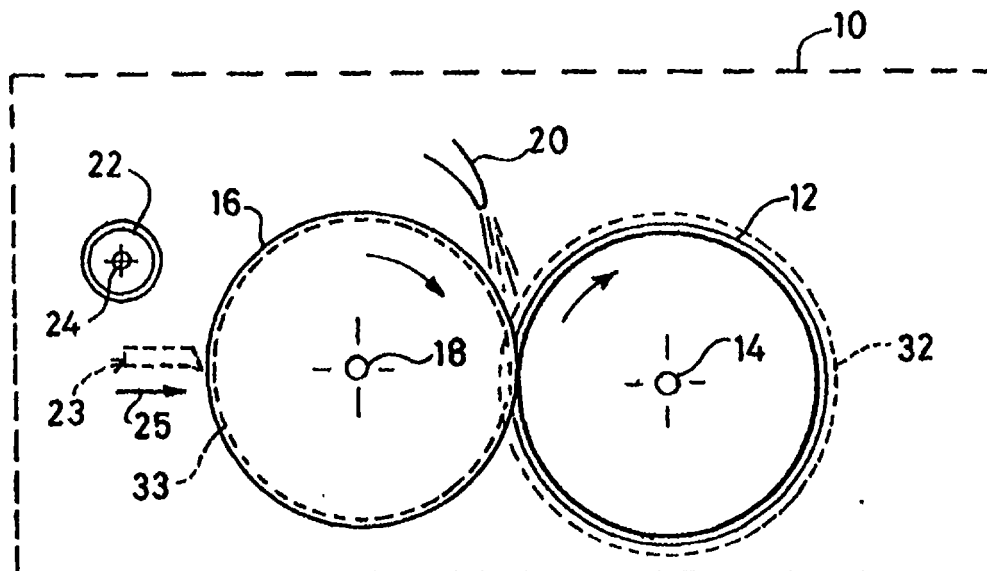


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(54) Title: WAFER EDGE POLISHING METHOD AND APPARATUS**(57) Abstract**

A semi-conductor wafer (12) has its inclined edge flanks polished by a grooved wheel (16) of synthetic plastics material, while a jet (20) of polishing slurry, which may comprise colloidal silica, is fed downwards into the zone of contact between the wheel and the wafer. The wheel (16) is preferably rocked or oscillated laterally such that a constant polishing force is alternatively applied to each flank of the wafer (12). The wheel may be mounted in a buffer store to which the wafers are transported from a grinding station which grinds the edge flanks.